MOSFET

英飞凌OptiMOS ™ 6功率 MOSFET，80 V

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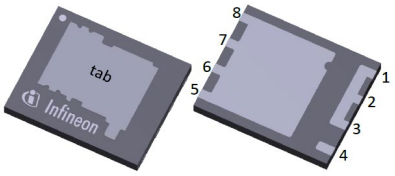
特性

- 双面冷却封装，具有最低的结顶热阻抗
- N沟道，标准电平
- 针对高性能 SMPS 进行了优化
- 出色的栅极电荷 和 $R_{DS(on)}$乘积 (FOM)
- 100% 雪崩测试
- 工作温度 175°C
- 无铅镀层；符合 RoHS 标准
- 符合 IEC61249-2-21 标准的无卤素

PG-WSON-8

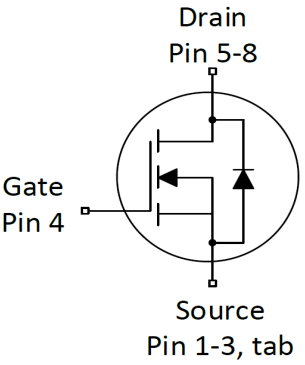


产品验证

已通过 JEDEC 相关测试。

表 1　　主要性能参数

Parameter	Value	Unit
V_{DS}	80	V
$R_{DS(on),max}$	2.5	mΩ
I_D	170	A
Q_{oss}	91	nC
Q_G (0V..10V)	46	nC
Q_{rr} (100A/µs)	72	nC



Hal Pb

RoHS

Part number	Package	Marking	Related links
ISC025N08NM6SC	PG-WSON-8	025N08SC	-

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1 最大额定值

除非另有规定，T_A =25 °C

表 2 最大额定值

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Continuous drain current [1]	I_D	-	-	170	A	V_{GS}=10 V, T_C=25 °C
				120		V_{GS}=10 V, T_C=100 °C
				108		V_{GS}=8 V, T_C=100 °C
				23		V_{GS}=10 V, T_A=25 °C, R_{THJA}=50 °C/W [2]
Pulsed drain current [3]	$I_{D,pulse}$	-	-	680	A	T_A=25 °C
Avalanche energy, single pulse [4]	E_{AS}	-	-	219	mJ	I_D=50 A, R_{GS}=25 Ω
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	-	-	167	W	T_C=25 °C
				3.0		T_A=25 °C, R_{THJA}=50 °C/W [2]
Operating and storage temperature	T_j, T_{stg}	-55	-	175	°C	-

[1] 额定值指产品仅依据数据手册指定的绝对最大值，保持外壳温度对于其他外壳温度请参见图 2。需要根据实际环境条件降低额定值。

[2] 器件置于40 mm × 40 mm × 1.5 mm 环氧树脂印刷电路板 FR4 上，配有6 cm^2（单层，70 µm厚）铜层面积用于漏极连接。印刷电路板垂直放置在静止空气中。

[3] 更多详细信息请参见图 3。

[4] 详细信息请参见图 13。

2 热特性

表 3 热特性

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case, bottom	R_{thJC}	-	0.45	0.90	°C/W	-
Thermal resistance, junction - case, top	R_{thJC}		0.43	0.86		
Thermal resistance, junction - ambient, 6 cm^2 cooling area [5)]	R_{thJA}		-	50		

[5)] 器件置于40 mm × 40 mm × 1.5 mm 环氧树脂印刷电路板 FR4 上，配有6 cm^2（单层，70 µm厚）铜层面积用于漏极连接。印刷电路板垂直放置在静止空气中。

3 电气特性

除非另有规定，T_j = 25°C

表 4 静态特性

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	80	-	-	V	V_{GS}=0 V, I_D=1 mA
Gate threshold voltage	$V_{GS(th)}$	2.4	3.0	3.5	V	V_{DS}=V_{GS}, I_D=81 µA
Zero gate voltage drain current	I_{DSS}	-	0.1	1	µA	V_{DS}=64 V, V_{GS}=0 V, T_j=25 °C
Zero gate voltage drain current [6]	I_{DSS}	-	10	100	µA	V_{DS}=64 V, V_{GS}=0 V, T_j=125 °C
Gate-source leakage current	I_{GSS}	-	10	100	nA	V_{GS}=20 V, V_{DS}=0 V
Drain-source on-state resistance	$R_{DS(on)}$	-	2.1	2.5	mΩ	V_{GS}=10 V, I_D=50 A
			2.6	3.15		V_{GS}=8 V, I_D=25 A
Gate resistance [6]	R_G	0.45	0.65	0.95	Ω	-
Transconductance [6]	g_{fs}	40	95	-	S	$\|V_{DS}\|\geq 2\|I_D\|R_{DS(on)max}$, I_D=50 A

[6] 由设计指定，

表 5 动态特性

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Input capacitance [7]	C_{iss}	-	3300	4000	pF	V_{GS}=0 V, V_{DS}=40 V, f=1 MHz
Output capacitance [7]	C_{oss}		1100	1380		
Reverse transfer capacitance [7]	C_{rss}		28	39		
Turn-on delay time	$t_{d(on)}$	-	15	-	ns	V_{DD}=40 V, V_{GS}=10 V, I_D=25 A, $R_{G,ext}$=1.6 Ω
Rise time	t_r		8.6			
Turn-off delay time	$t_{d(off)}$		22			
Fall time	t_f		5.3			

[7] 由设计指定，

表 6 栅极电荷特性 [8)]

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Gate to source charge [9)]	Q_{gs}	-	16	19	nC	V_{DD}=40 V, I_D=25 A, V_{GS}=0 to 10 V
Gate charge at threshold [9)]	$Q_{g(th)}$		9.8	11.8	nC	
Gate to drain charge [9)]	Q_{gd}		9.3	13	nC	
Switching charge	Q_{sw}		16	-	nC	
Gate charge total [9)]	Q_g		46	55	nC	
Gate plateau voltage	$V_{plateau}$		4.9	-	V	
Output charge [9)]	Q_{oss}	-	91	114	nC	V_{DS}=40 V, V_{GS}=0 V

[8)] 栅极电荷参数定义见图 16。

[9)] 由设计指定。

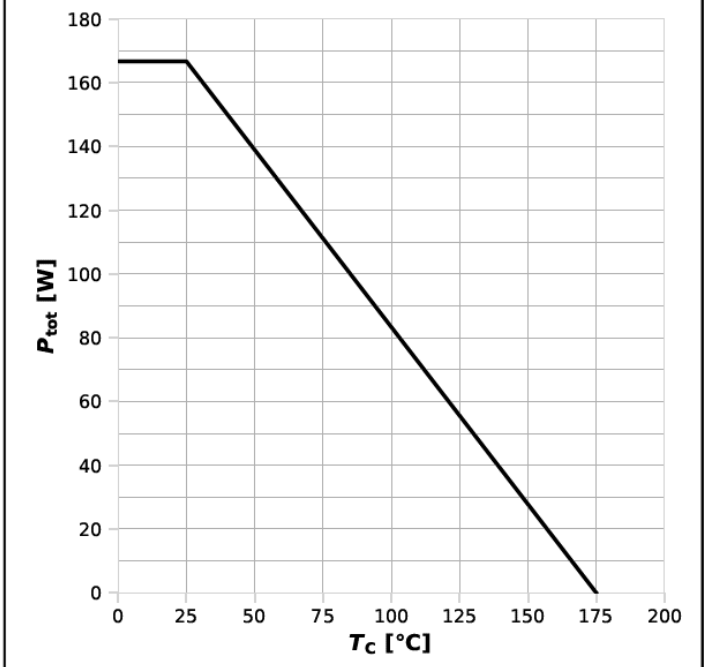
表 7 反向二极管

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Diode continuous forward current [10)]	I_S	-	-	155	A	T_C=25 °C
Diode pulse current [10)]	$I_{S,pulse}$			680		
Diode forward voltage	V_{SD}	-	0.81	1.0	V	V_{GS}=0 V, I_F=50 A, T_j=25 °C
Reverse recovery time [10)]	t_{rr}	-	51	77	ns	V_R=40 V, I_F=25 A, di_F/dt=100 A/µs
Reverse recovery charge [10)]	Q_{rr}		72	108	nC	
Reverse recovery time [10)]	t_{rr}	-	28	42	ns	V_R=40 V, I_F=25 A, di_F/dt=1000 A/µs
Reverse recovery charge [10)]	Q_{rr}		302	453	nC	

[10)] 由设计指定

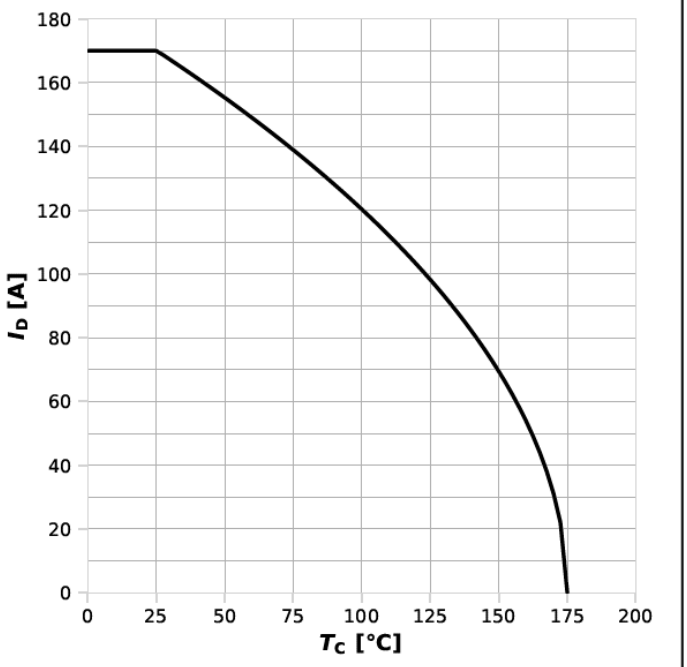
4 电气特性图

Diagram 1: Power dissipation



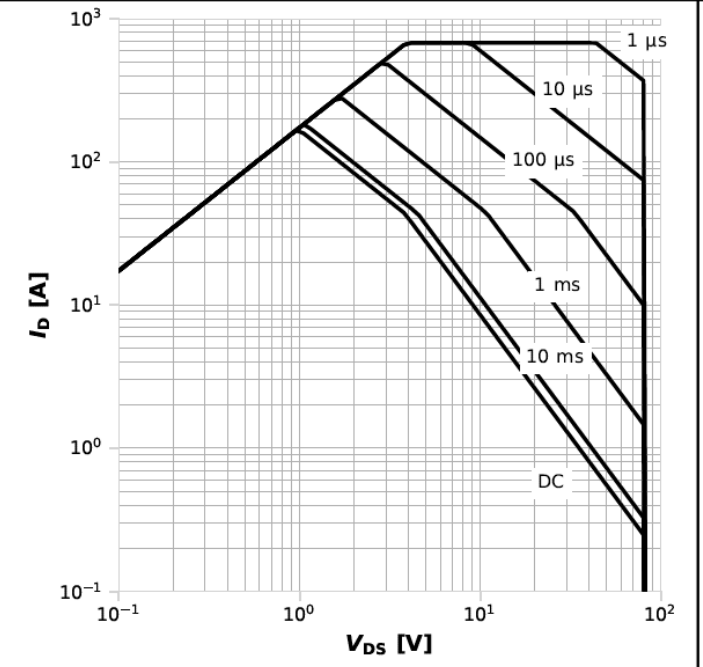
$P_{tot}=f(T_C)$

Diagram 2: Drain current



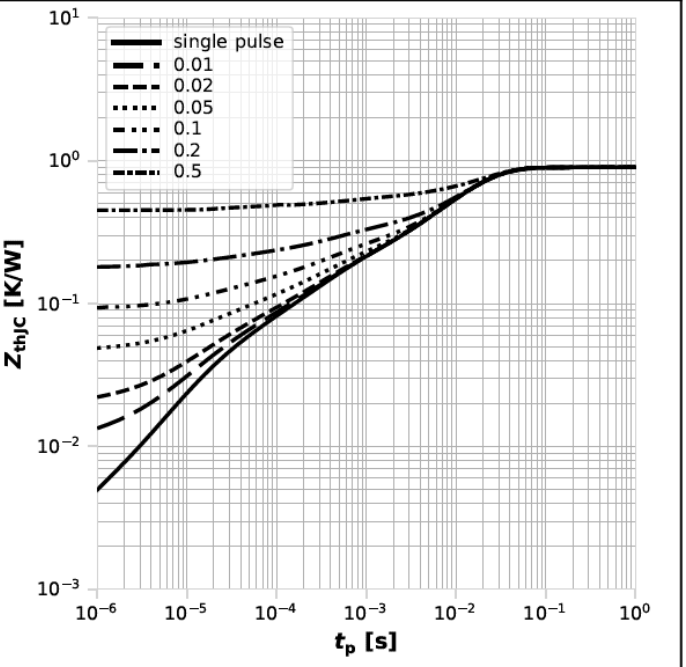
$I_D=f(T_C)$; $V_{GS}\geq 10$ V

Diagram 3: Safe operating area



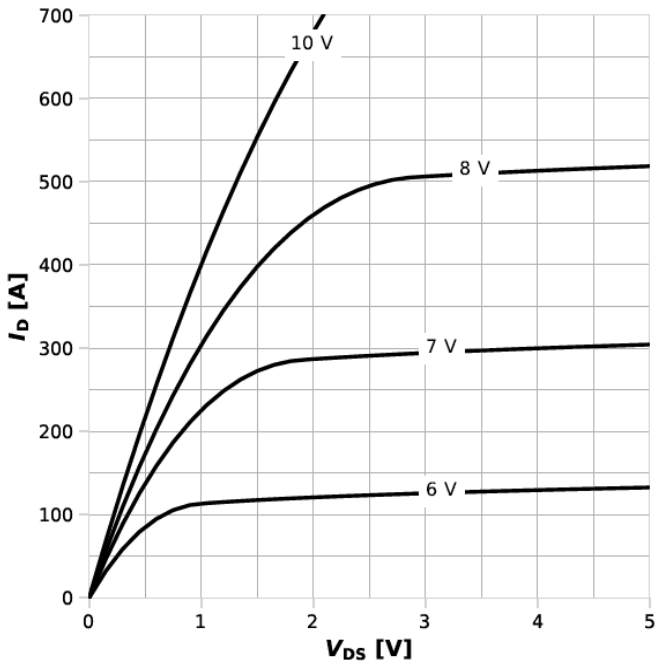
$I_D=f(V_{DS})$; $T_C=25$ °C; $D=0$; parameter: t_p

Diagram 4: Max. transient thermal impedance



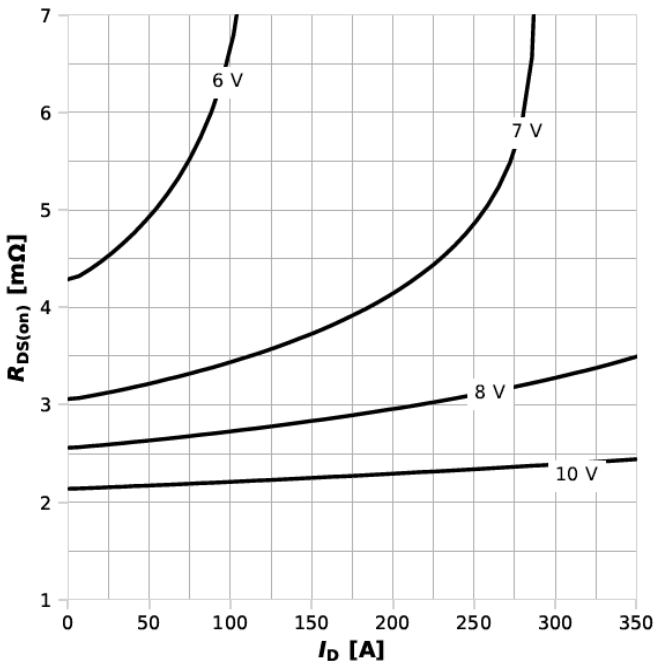
$Z_{thJC}=f(t_p)$; parameter: $D=t_p/T$

Diagram 5: Typ. output characteristics



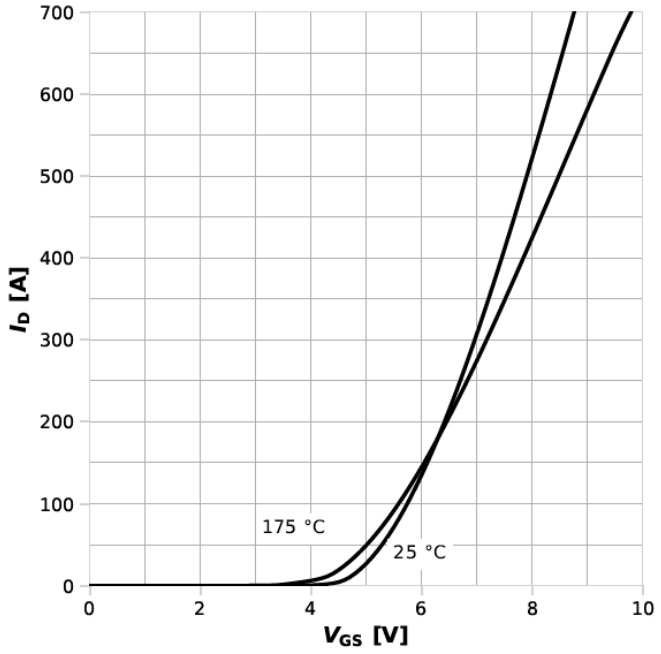
I_D=f(V_{DS}), T_j=25 °C; parameter: V_{GS}

Diagram 6: Typ. drain-source on resistance



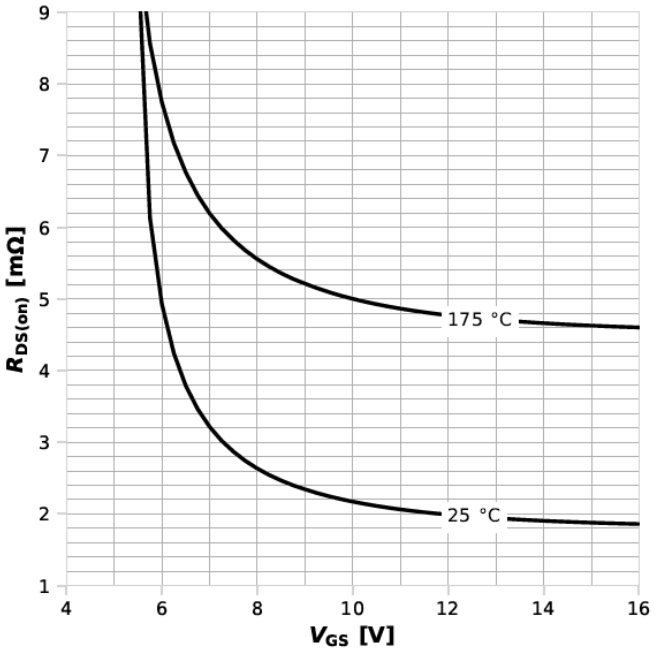
$R_{DS(on)}$=f(I_D), T_j=25 °C; parameter: V_{GS}

Diagram 7: Typ. transfer characteristics



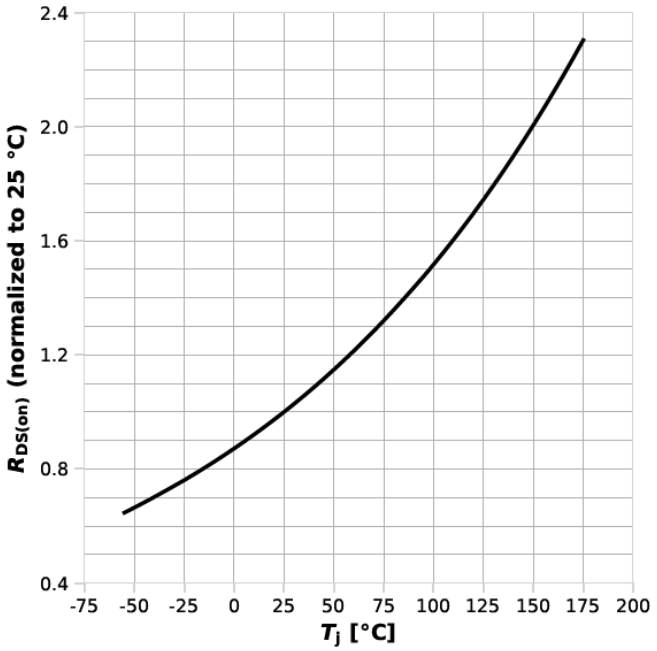
I_D=f(V_{GS}), $|V_{DS}|>2|I_D|R_{DS(on)max}$; parameter: T_j

Diagram 8: Typ. drain-source on resistance



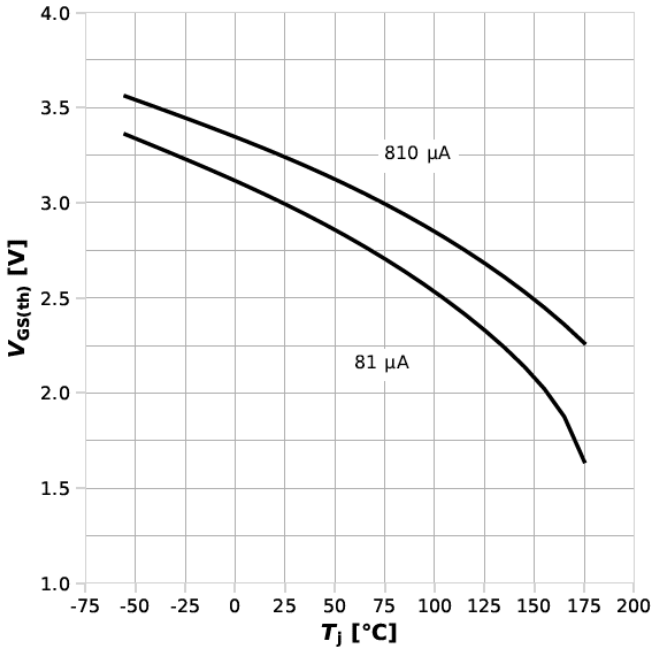
$R_{DS(on)}$=f(V_{GS}), I_D=50 A; parameter: T_j

Diagram 9: Normalized drain-source on resistance



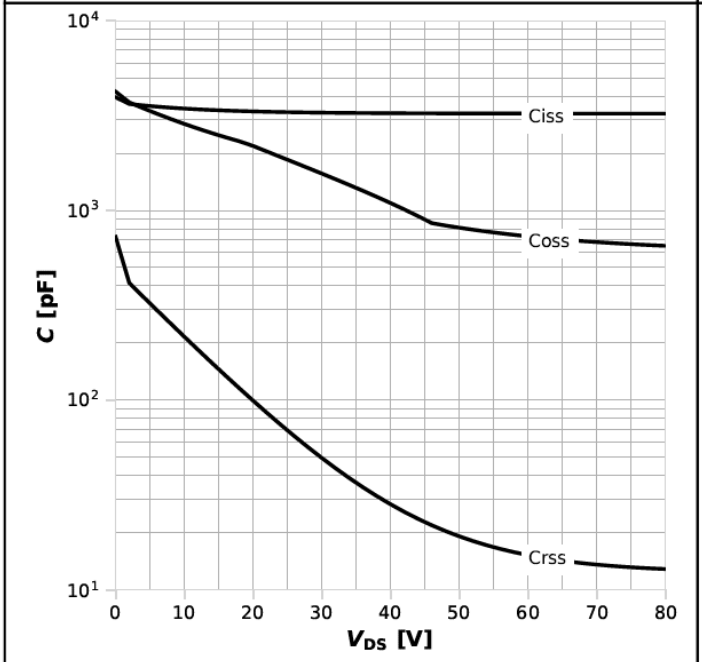
$R_{DS(on)}$=f(T_j), I_D=50 A, V_{GS}=10 V

Diagram 10: Typ. gate threshold voltage



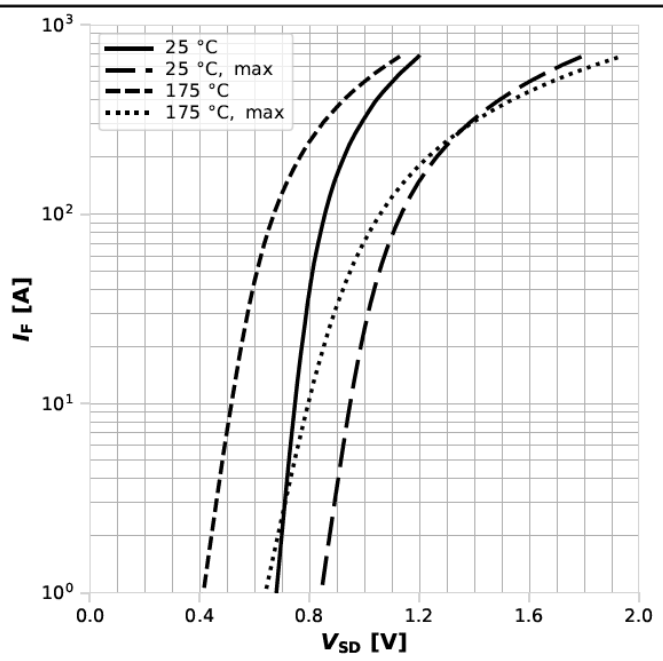
$V_{GS(th}$=f(T_j), V_{GS}=V_{DS}; parameter: I_D

Diagram 11: Typ. capacitances



C=f(V_{DS}); V_{GS}=0 V; f=1 MHz

Diagram 12: Forward characteristics of reverse diode



I_F=f(V_{SD}); parameter: T_j

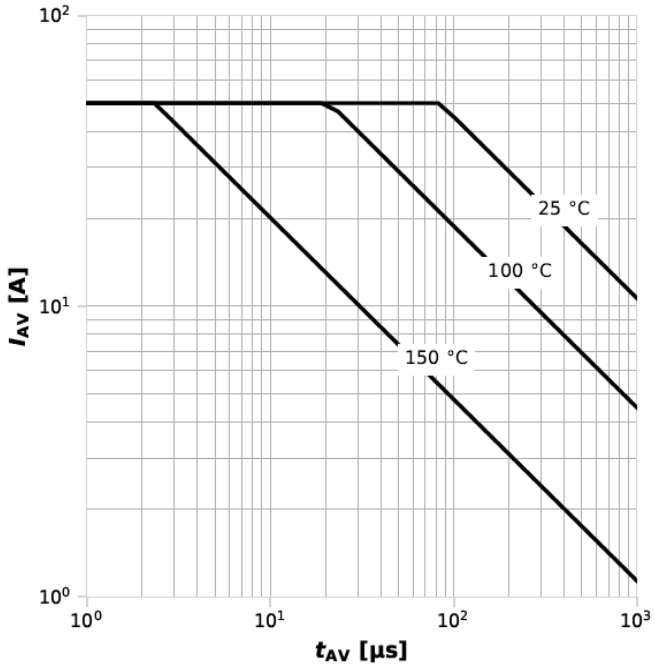
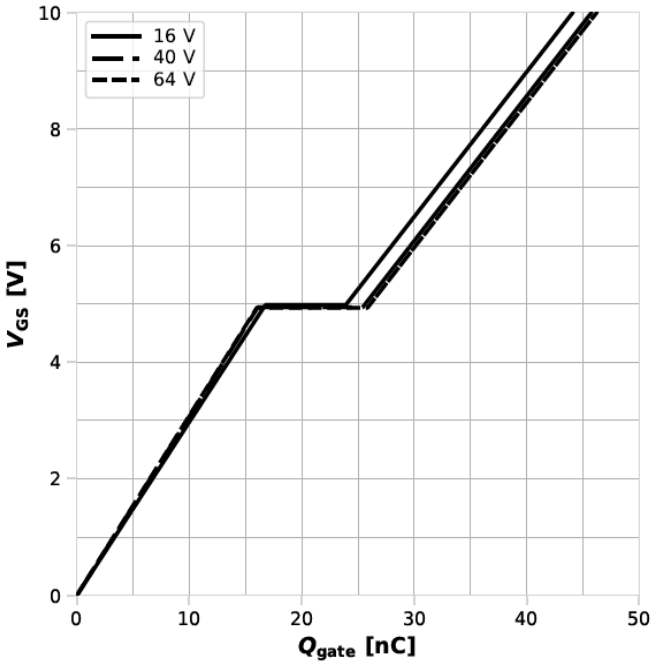
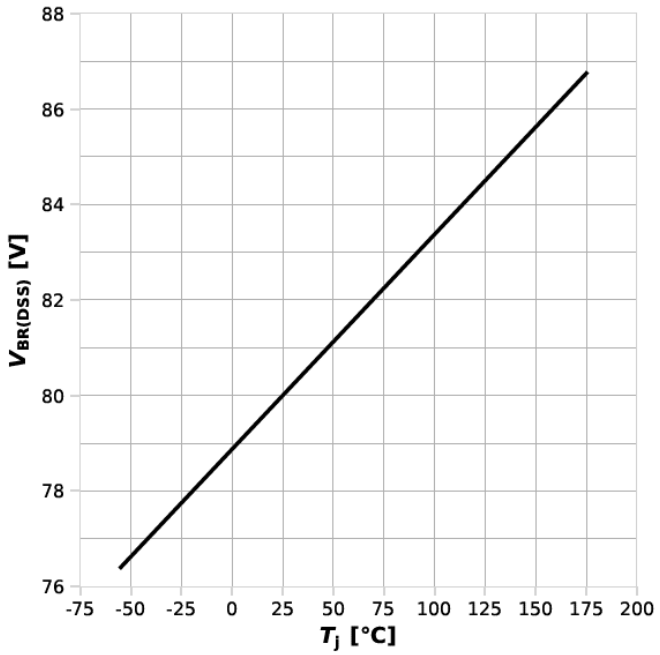
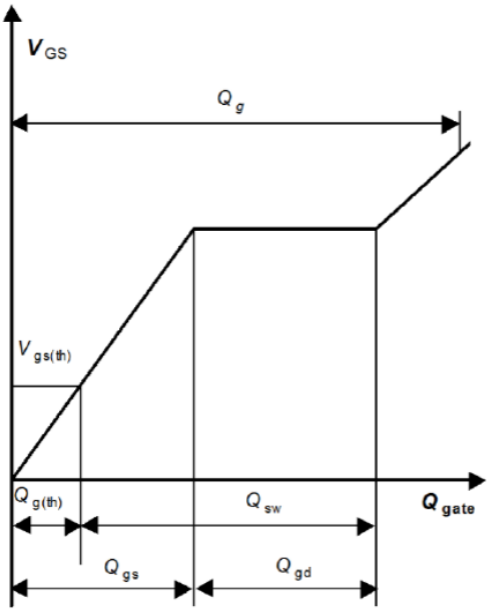
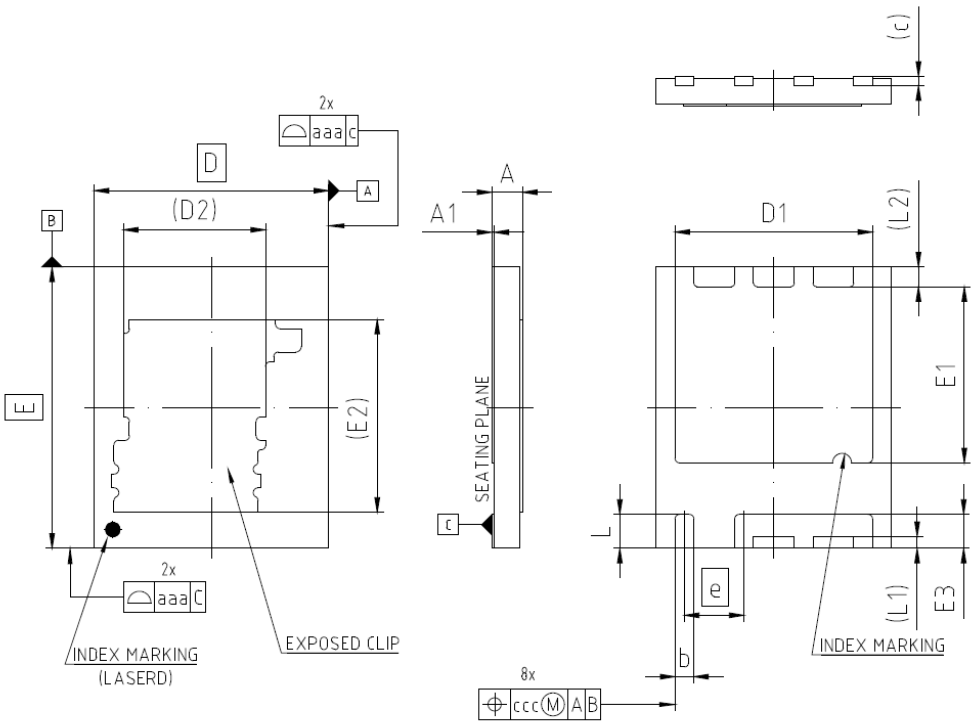
Diagram 13: Avalanche characteristics	Diagram 14: Typ. gate charge
	
I_{AS}=f(t_{AV}); R_{GS}=25 Ω; parameter: $T_{j,start}$	V_{GS}=f(Q_{gate}), I_D=25 A pulsed, T_j=25 °C; parameter: V_{DD}

Diagram 15: Drain-source breakdown voltage	Gate charge waveforms
	
$V_{BR(DSS)}$=f(T_j); I_D=1 mA	-

5 封装外形



PACKAGE - GROUP NUMBER:	PG-WSON-8-U01				
DIMENSIONS	MILLIMETERS		DIMENSIONS	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.55	0.75	e	1.27	
A1	0.00	0.05	L	0.68	0.78
b	0.35	0.45	L1	0.25	
c	0.20		L2	0.42	
D	5.00		aaa	0.05	
D1	4.11	4.31	ccc	0.10	
D2	3.03				
E	6.00				
E1	3.66	3.86			
E2	4.11				
E3	0.63	0.83			

NOTE: DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS

图 1　　PG-WSON-8 外形图，尺寸单位为毫米

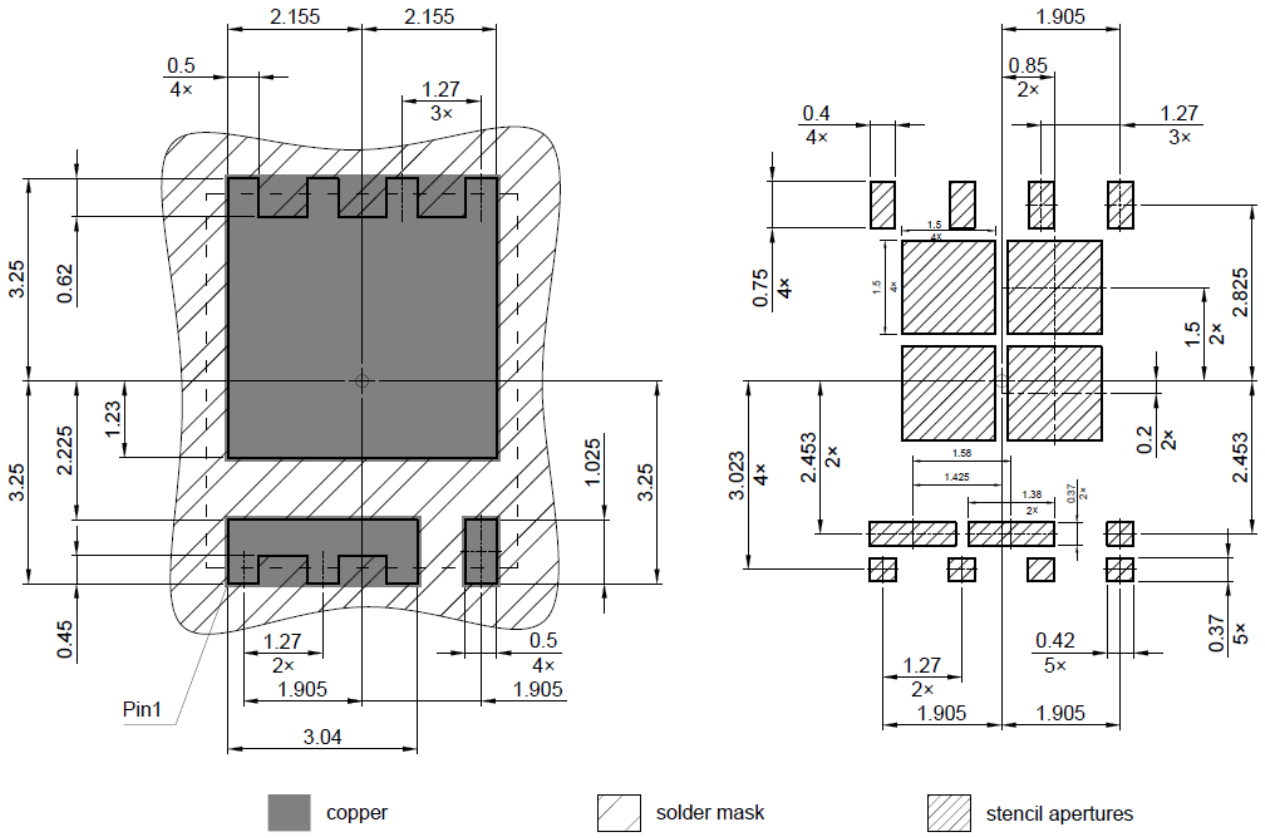


图 2　　PG- WSON- 8 封装图，尺寸单位为毫米

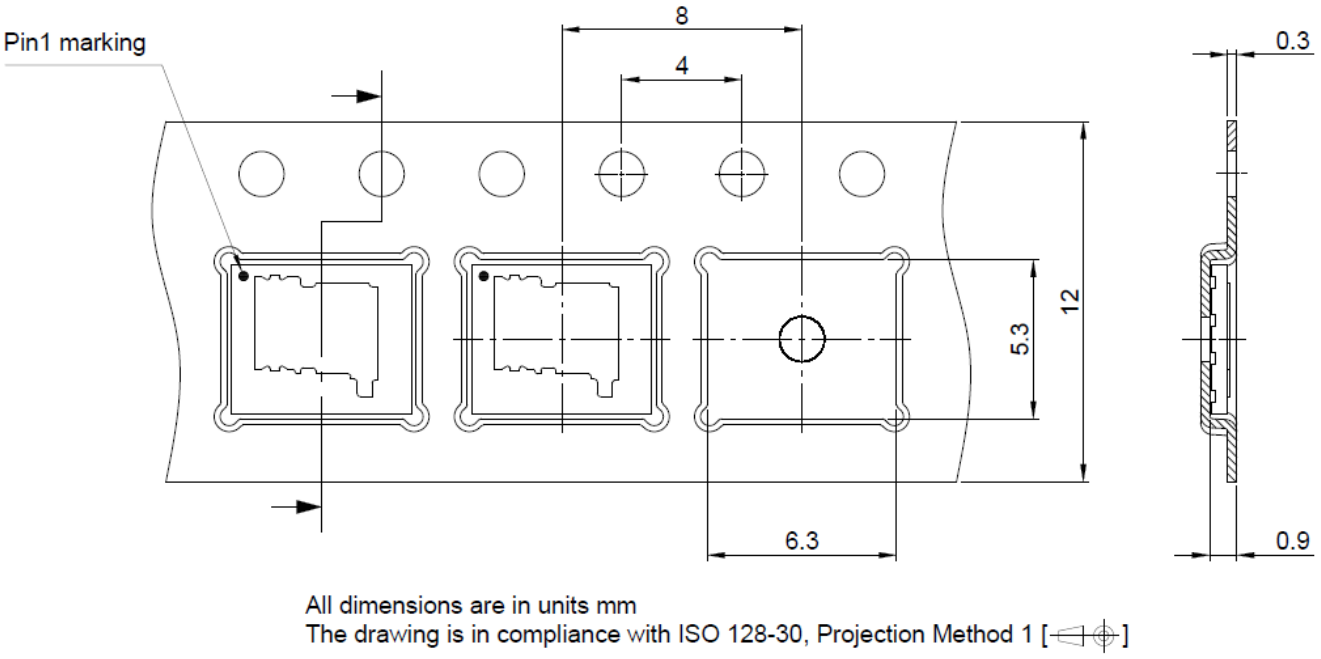


图 3　　PG-WSON-8 包装型号，尺寸单位为毫米

修订记录

ISC025N08NM6SC

Revision 2026 - 03 - 16 , Rev. 1 . 0

Previous revisions

Revision	Date	Subjects (major changes since last revision)
1.0	2026-03-16	Release of final version

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